

AMENDMENTS TO THE SPECIFICATION

Please replace the first paragraph on page 1 with the following amended paragraph:

CROSS-REFERENCE TO RELATED APPLICATION

This patent application claims priority to U.S. Provisional Patent Application, Serial Number 60/458,467, filed on March 28, 2003, and is related to U.S. Utility Patent Application, Serial Number, 09/730,130, filed December 4, 2000, now Patent No. 6,586,954, entitled “PROBE TILE FOR PROBING SEMICONDUCTOR WAFER”; U.S. Provisional Patent Application, Serial Number 60/392,394, filed June 28, 2002, entitled “SHIELDED PROBE APPARATUS FOR PROBING SEMICONDUCTOR WAFER”; and U.S. Utility Patent Application, Serial Number 10/383,079, filed March 6, 2003, entitled “APPARATUS AND METHOD FOR TERMINATING PROBE APPARATUS OF SEMICONDUCTOR WAFER”; the subject matter of which are incorporated herewith by reference.

Please replace the fourth paragraph on page 6 beginning at line number 25 with the following amended paragraph:

As also shown in Figure 1, the connection or contact between the probe needle 101 side and the connector or signal cable (not shown) side is head on head. Alternatively, the connection or contact between the probe needle 101 side and a connector or signal cable 107 side is side-by-side as shown in Figures 5 and 6, which are disclosed in U.S. Utility Patent Application, S/N 10/383,079, filed March 6, 2003, subject matter of which are incorporated herewith by reference. Figure 2 illustrates a masking technique for masking a probe needle 201. As shown, masking materials 202 and 203 are applied to the ends of the probe needle 201 to prevent the conductive driven guard layer 103, such as the conductive driven guard layer 103 in Figure 1, from depositing over the end of the dielectric creating a conductive path between the conductive guard layer 103 and the probe needle 201. The masks are applied towards the ends of the probe needle necessary to provide required access and protection.